

Shenzhen Yishengbang Technology Co., LTD

Sample acceptance letter SPECIFICATION FOR APPROVAL

The name of the company: Xianzhiwulian

The material code: _____

specifications: _____

Admitted to date: _____

The name of the supplier: Shenzhen Yishengbang Technology Co., LTD

Supplier standard type number: RANT2012F245C02

Acceptance stamp					
For acceptance by the contractor			Xianzhiwulian		
Rf Engineer	audit	approval	Rf Engineer	audit	approval
cai liang Liu	Zhen Huang	Mei Cai Lin			
Signed and sealed			Signed and sealed		
date		2025-5-20	date		
instructions: ☐ accept ☐ Conditional acceptance					
note:					

The name of the supplier: Shenzhen Yishengbang Technology Co., LTD

Supplier address: 101, Building C, Shenzhen Qianwan Hard Technology Industrial Park,
Bao 'an District, Shenzhen

telephone: 18025305599

telephone: 18666299104

2.4GHz 2012 Chip Antenna: RANT2012F245C02

Application:

WLAN, 802.11b/g, Bluetooth, WLAN, etc...

Features

SMD, high reliability, ultra Impact, Omni-directional...



Part number Information

RANT 2012 F 245 C 02
(A) (B) (C) (D) (E) (F)

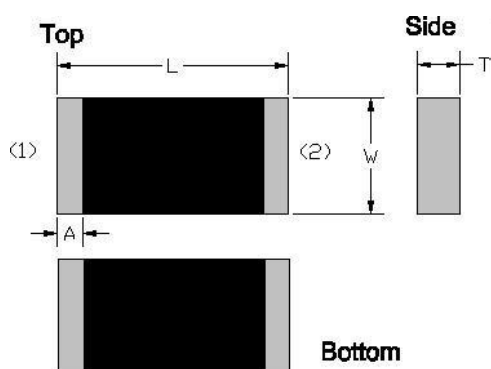
(A)Product Type	Chip Antenna
(B) Size Code	2.0x1.2mm(+/-0.2mm)
(C) Material	High K material
(D) Frequency	2.4 ~ 2.5GHz
(E) Feeding mode	PIFA & Single Feeding
(F) Antenna type	Type=02

Electrical Specification

Working Frequency Range	2400 ~2484 MHz
Bandwidth	84 (Min.)
Peak Gain	1.95 dBi (Typ.)
Impedance	50 Ohm
Return loss	10 dB (Min)
Polarization	Linear
Azimuth Beamwidth	Omni-directional
Operation Temperature(°C)	-40 ~85°C
Resistance to Soldering Heats	10sec. (@ 280°C)
Termination	Ni / Au (Leadless)

The specification is defined on EVB.

Dimension and Terminal Configuration

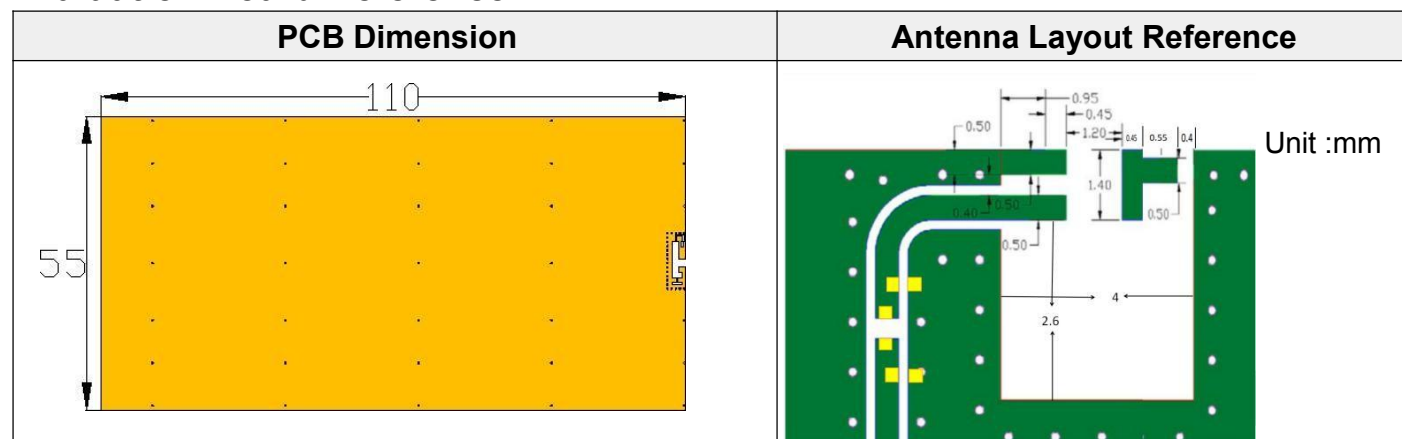


Dimension (mm)	
L	2.05+/-0.15
W	1.20+/-0.15
T	0.45+/-0.10

No.	Terminal Name
1	Feeding/GNG
2	GND

2.4GHz 2012 Chip Antenna: RANT2012F245C02

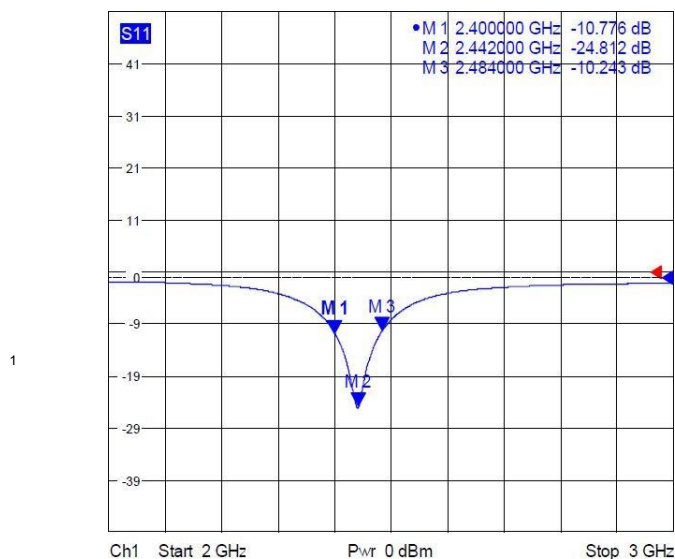
Evaluation Board Reference



Electrical Characteristics

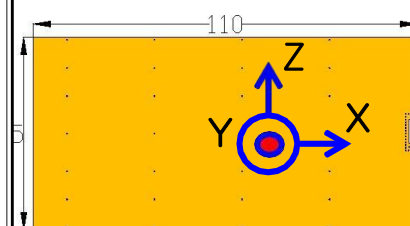
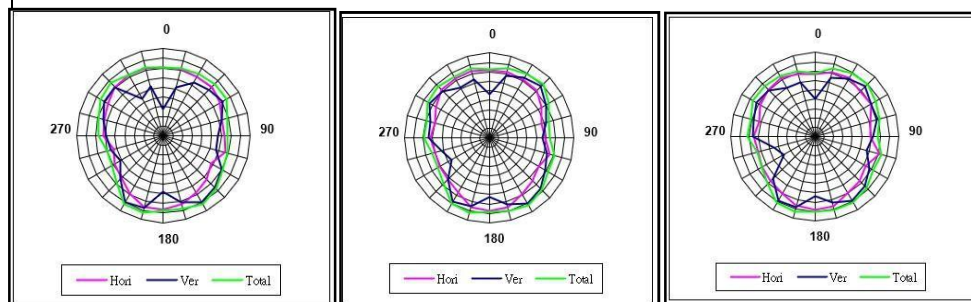
Return Loss & Radiation

Return Loss

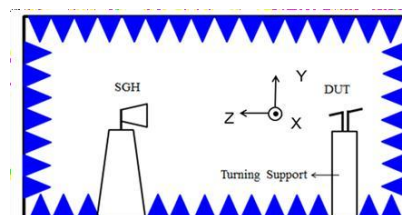


Frequency(MHz)	S11 (dB)
2400	-10.77
2450	-24.81
2484	-10.243

Radiation

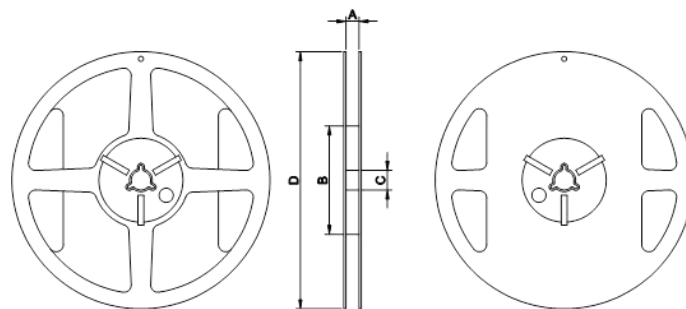


	2400MHz	2450MHz	2500MHz
Efficiency	70.56%	75.25%	71.01%
Peak Gain	1.72 dBi	1.95 dBi	1.69 dBi
Directivity	2.26 dBi	2.69 dBi	2.11 dBi



Reel and Taping Specification

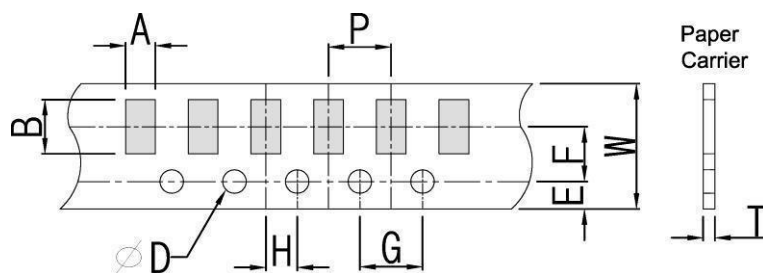
Reel Specification



7" x 8 mm

TYPE	SIZE		A	B	C	D
2012	7"	5K/Reel	9.0±0.5	60±2	13.5±0.5	178±2

Tapping Specification



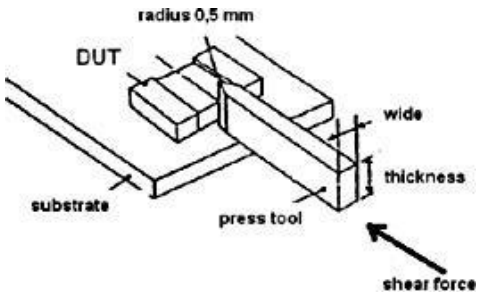
Packaging	Type	A	B	W	E	F	G	H	T	D	P
Paper Type	2012	1.50±0.20	2.30±0.20	8.0±0.20	1.75±0.10	3.5±0.05	4.0±0.10	2.0±0.05	0.75±0.10	1.57±0.10	4.0±0.1

2.4GHz 2012 Chip Antenna: RANT2012F245C02

Reliability Table

Test Item	Procedure	Requirements Ceramic Type	Remark (Reference)
Electrical Characterization		Fulfill the electrical specification	User Spec.
Thermal Shock	1. Preconditioning: $50 \pm 10^{\circ}\text{C}$ / 1 hr , then keep for 24 ± 1 hrs at room temp. 2. Initial measure: Spec: refer Initial spec. 3. Rapid change of temperature test: -30°C to $+85^{\circ}\text{C}$; 100 cycles; 15 minutes at Lower category temperature; 15 minutes at Upper category temperature.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 107
Temperature Cycling	1. Initial measure: Spec: refer Initial spec. 2. 100 Cycles (-30°C to $+85^{\circ}\text{C}$), Soak Mode=1 (2 Cycle/hours). 3. Measurement at 24 ± 2 Hours after test condition.	No Visible Damage. Fulfill the electrical specification.	JESD22 JA104
High Temperature Exposure	1. Initial measure: Spec: refer Initial spec. 2. Unpowered; 500hours @ $T=+85^{\circ}\text{C}$. 3. Measurement at 24 ± 2 hours aftertest.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 108
Low Temperature Storage	1. Initial measure: Spec: refer Initial spec. 2. Unpowered: 500hours @ $T=-30^{\circ}\text{C}$. 3. Measurement at 24 ± 2 hours aftertest.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 108
Solderability (SMD Bottom Side)	Dipping method: a. Temperature: $235 \pm 5^{\circ}\text{C}$ b. Dipping time: $3 \pm 0.5\text{s}$	The solder should cover over 95% of the critical area of bottom side.	IEC 60384-21/22 4.10
Soldering Heat Resistance (RSH)	Preheating temperature: $150 \pm 10^{\circ}\text{C}$. Preheating time: 1~2 min. Solder temperature: $260 \pm 5^{\circ}\text{C}$. Dipping time: $5 \pm 0.5\text{s}$	No Visible Damage.	IEC 60384-21/22 4.10
Vibration	5g's for 20 min., 12 cycles each of 3 orientations Note: Use 8"X5" PCB .031" thick 7 secure points on, one long side and 2 secure points at corners of opposite sides. Parts mounted within 2" from any secure point. Test from 10-2000 Hz.	No Visible Damage.	MIL-STD-202 Method 204
Mechanical Shock	Three shocks in each direction shall be applied along the three mutually perpendicular axes of the test specimen (18 shocks) Peak value: 1,500g's Duration: 0.5ms Velocity change: 15.4 ft/s Waveform: Half-sine	No Visible Damage.	MIL-STD-202 Method 213
Humidity Bias	1. Humidity: 85% R.H., Temperature: $85 \pm 2^{\circ}\text{C}$. 2. Time: 500 ± 24 hours. 3. Measurement at 24 ± 2 hrs after testcondition.	No Visible Damage. Fulfill the electrical specification.	MIL-STD-202 Method 106

2.4GHz 2012 Chip Antenna: RANT2012F245C02

Board Flex (SMD)	1. Mounting method: IR-Reflow. PCB Size (L:100 × W:40 × T:1.6mm) 2. Apply the load in direction of the arrow until bending reaches 2 mm.	No Visible Damage.	AEC-Q200 005
Adhesion	Force of 1.8Kg for 60 seconds. 	No Visible Damage Magnification of 20X or greater may be employed for inspection of the mechanical integrity of the device body terminals and body/terminal junction.	AEC-Q200 006
Physical Dimension	Any applicable method using x10 magnification, micrometers, calipers, gauges, contour projectors, or other measuring equipment, capable of determining the actual specimen dimensions.	In accordance with specification.	JESD22 JB100

Revision History

Revision	Date	Content
1	2020/10/15	New Datasheet